Design Feedback

March 20th 2016

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Summary

NextInput makes the following recommendations:

- Move sensors as far away from the bond area as possible

- Minimize bond area in the upper/lower regions of the phone

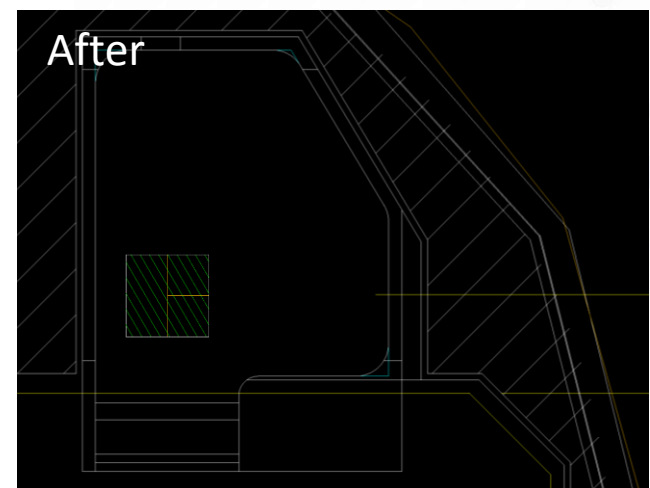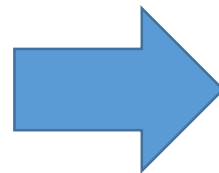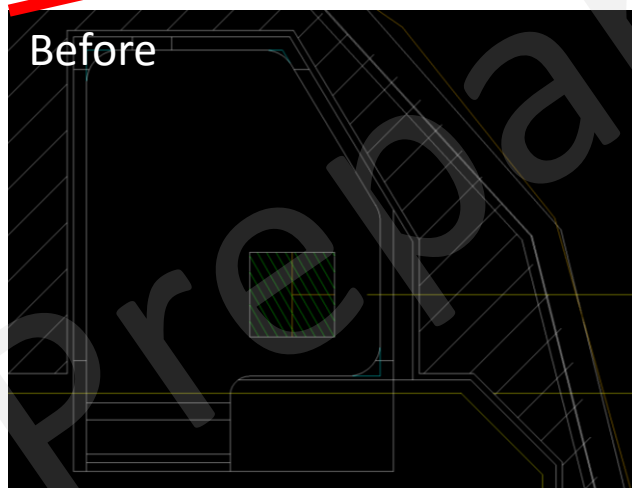- Avoid "Bottoming Out" of Display and Glass on any other component

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Move Sensors Far Away From Bond

Set outline
Tape 영역
Force Sensor Position
LCD Outline

60.3
30.15
1.51

Area of Detail

Before

After

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Move Sensors Far Away From Bond

Before

After

Area of Detail

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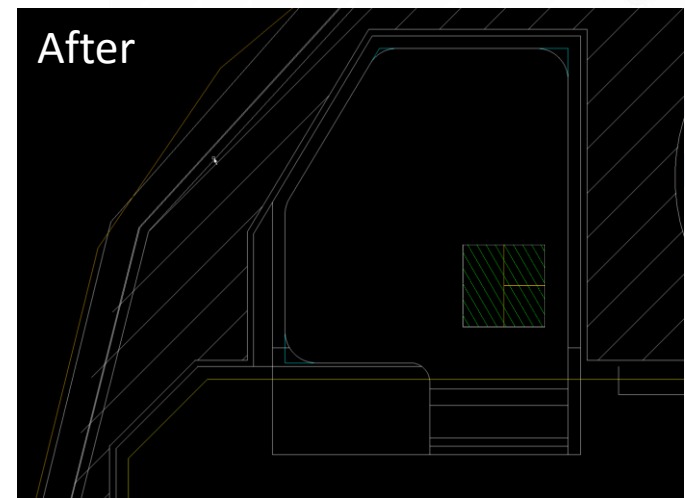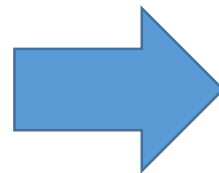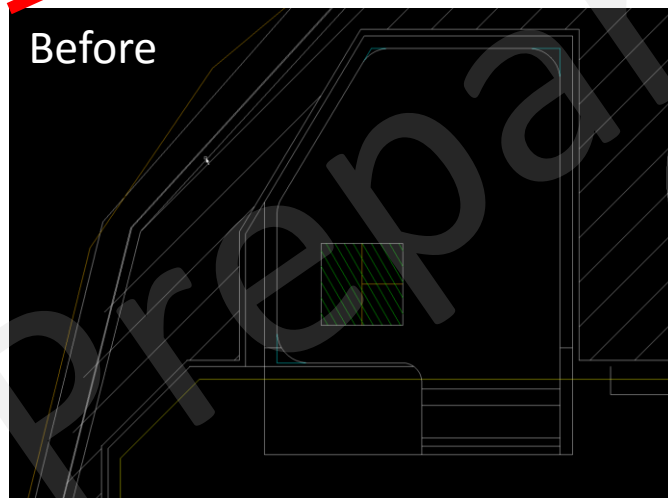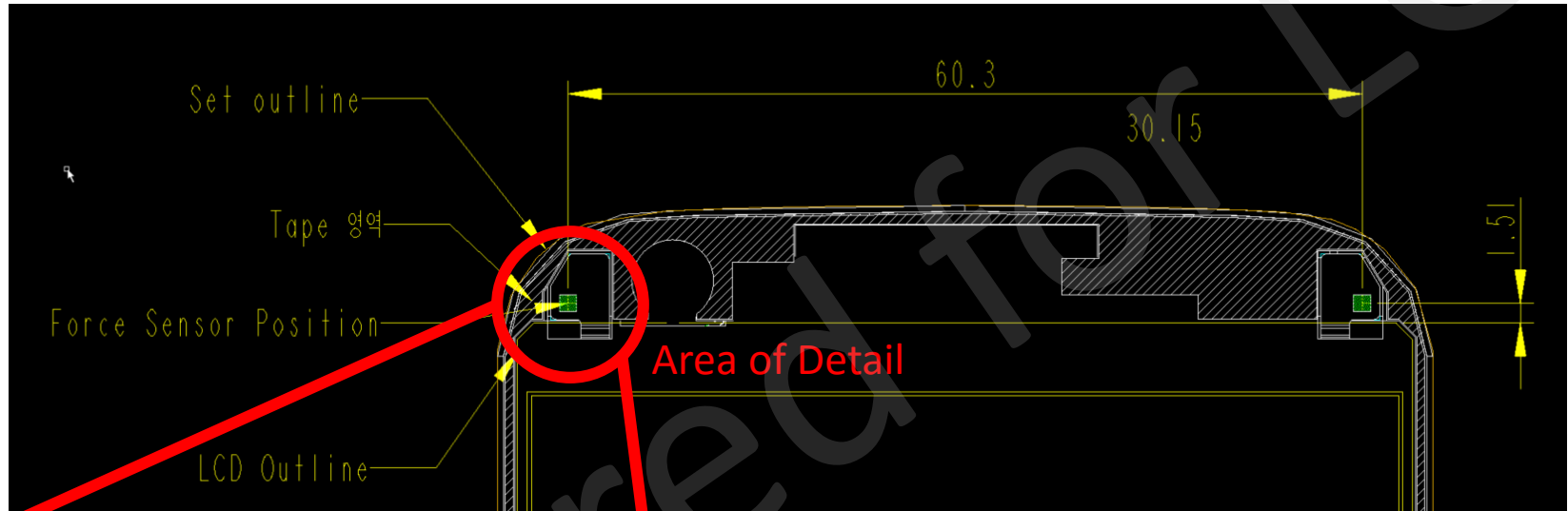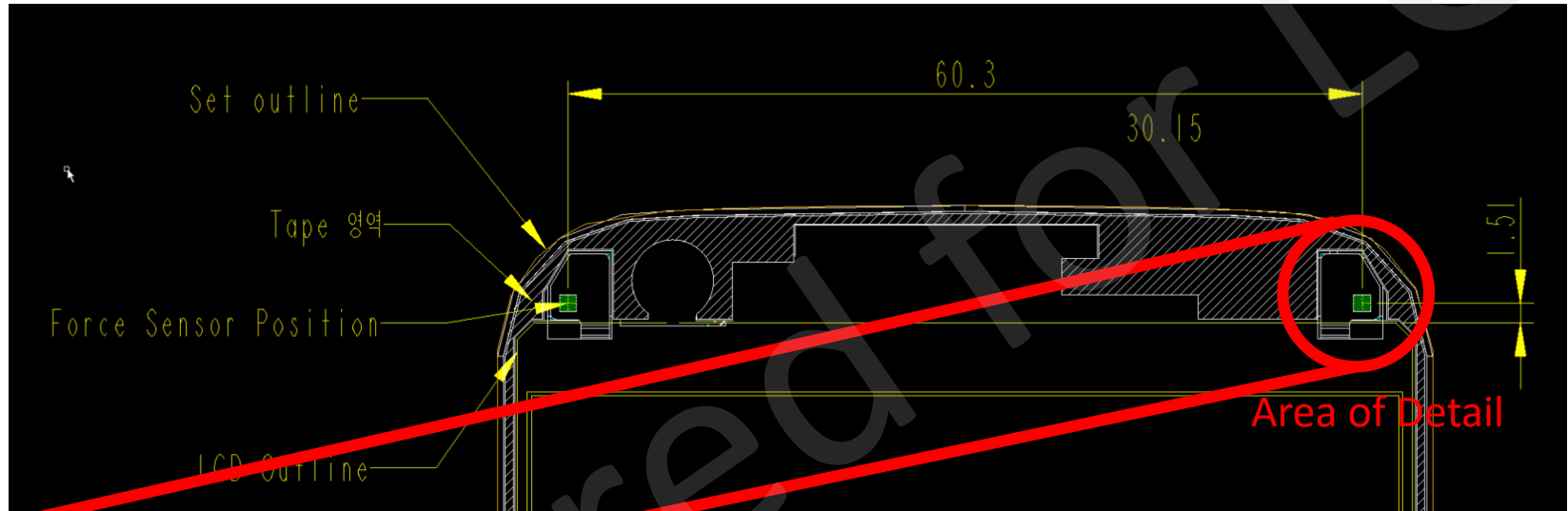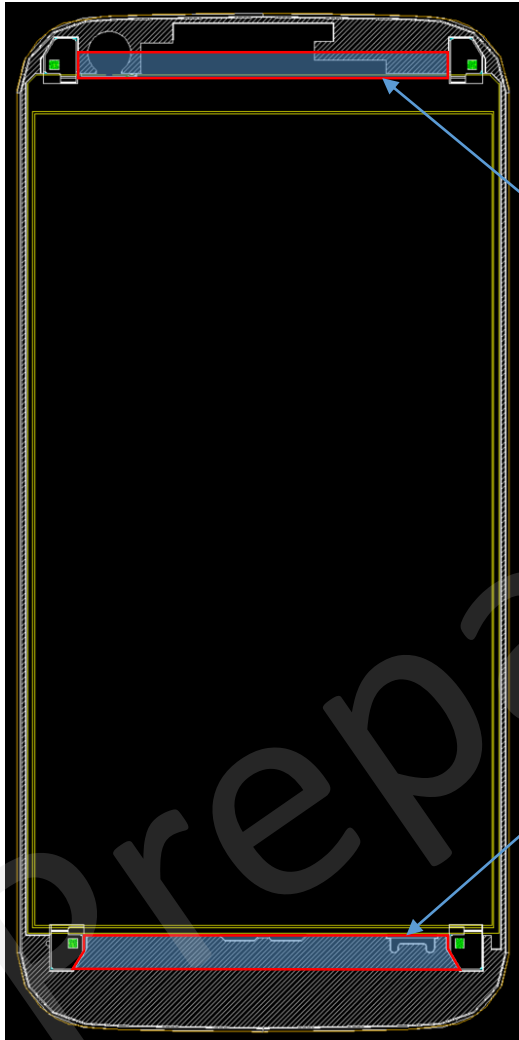
Minimize Bond Area

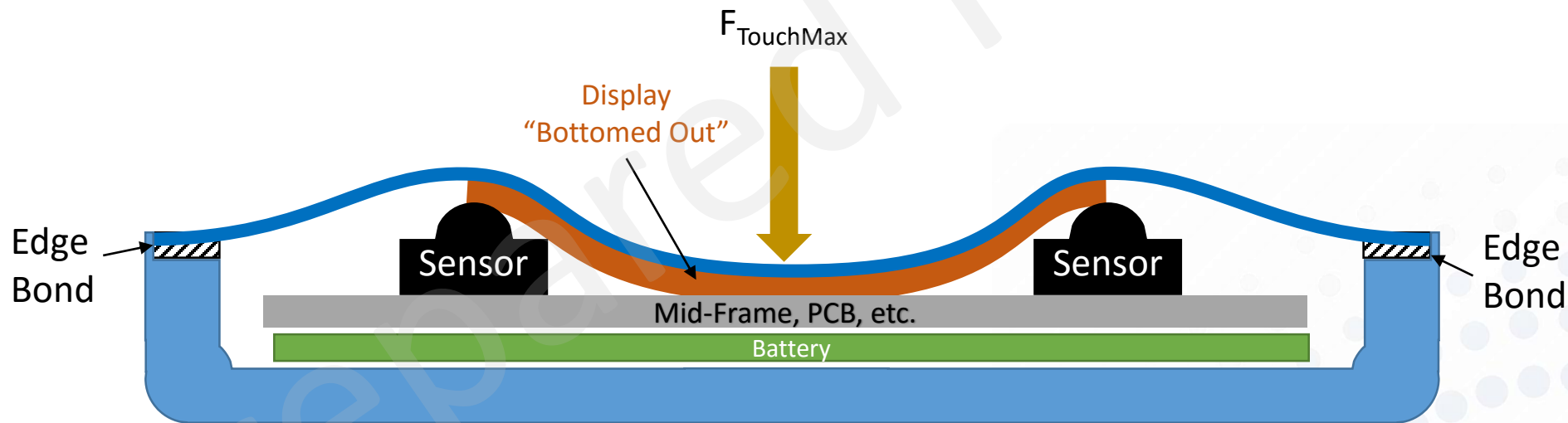Remove this bond area and the plastic material underneath it to minimize shunt forces and ensure glass does not "bottom out" on plastic

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Avoid "Bottoming Out" Display

Min Gap must be engineered so that at $F_{TouchMax}$ in the center of the glass, display does not touch any other part:
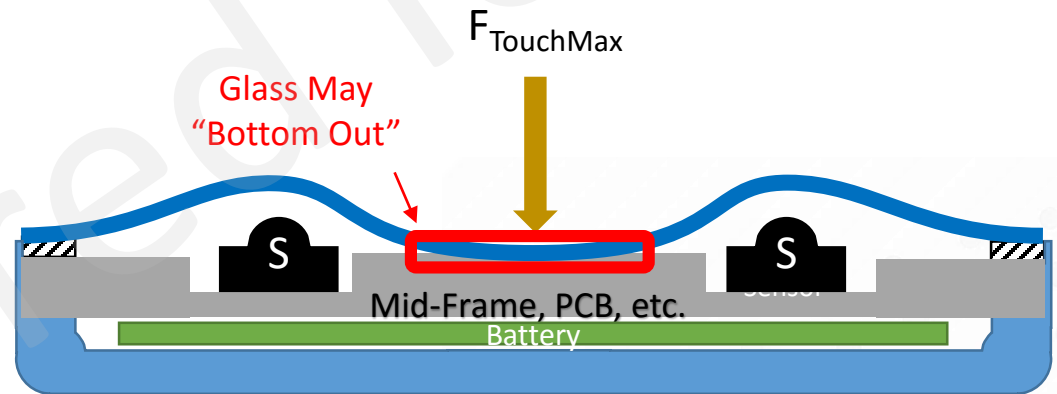
$F_{TouchMax}$

Display "Bottomed Out"

Edge Bond

Sensor

Sensor

Mid-Frame, PCB, etc.

Battery

Edge Bond

Note: Cross Section Not to Scale. Deformation is exaggerated for clarity.
Other components omitted for clarity.

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Avoid "Bottoming Out" Glass

Cross Section A-A:

$F_{TouchMax}$

Glass May "Bottom Out"

Mid-Frame, PCB, etc.

Battery

Sensor

Glass May "Bottom Out"

A --------- A

Note: Cross Section Not to Scale.
Deformation is exaggerated for clarity.
Other components omitted for clarity.

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